**PCB Fabrication Process Engineering Contact Sheet**

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| Project Name (Version) | Polyhex 24PIN-Pai 15PIN V01-20250522-Process Document | | | | | |
| Contact Person |  | Email |  | | Tel |  |
| Panelization Method | Non-panelized | | | | | |
| Board Thickness | 0.2mm+/-10% | Layer | 2 | Material | FPC (Flexible Printed Circuit) | |
| Board Dimensions | 15\*1.6mm | | | | | |
| PCB Specifications | 1. ENIG (Electroless Nickel Immersion Gold) Process | | | | | |
| 1. ENIG Copper Thickness: 1 oz | | | | | |
| 1. Coverlay Color: Yellow; Coverlay Thickness: 25μm | | | | | |
| 1. Silkscreen: White | | | | | |
| 1. Compliant with Lead-free & RoHS Requirements | | | | | |
| 1. PI Stiffener Application | | | | | |
| 1. Stiffener Thickness: 0.15mm | | | | | |
| Warpage/Twist | IPC 6012 Class 2, ≤0.5% | | | | | |
| Packaging | Mark defective boards with "X" on both sides and package separately. | | | | | |
| Electrical Testing | Score board edges for passed E-test units. | | | | | |
| Unspecified Fabrication Standards | Follow IPC 6012 & 6016 Class 2 for unspecified requirements. | | | | | |
| Copper Foil, Stackup, Impedance As per Gerber file data. | | | | | | |

PI Stiffener on Gold Finger Backside (FPC Ends)

